

深圳市康华尔电子有限公司

SHENZHEN KONUAER ELECTRONICS CO.,LTD

樣品承認書

SAMPLE APPROVAL SHEET

	CUS	гомек:			-			
	SIZE	UP:	表面谐	振器				
	Volu	ıme:	R43	33.92M				
	NUM	IBER:	SMD3	030mm	_			
	DATE:				_			
承認後請寄回一份 PLS SEND BACK ONE COPY TO US AFTER YOUR APPROVAL								
承認結果	客戶簽名 客戶承		章 日期		備注			
CONCLUSION	SIGNATURE	STAMP		DATE	REMARK			
合格								
ACCEPT								
不合格								
REJECT								
制表: JACK LIU/			审核:					
					(公章)			
尊敬的客户:请您抽品	出一点时间,在7-10个	工作日内将承认书回签	<i>,若未回签</i>	以视默认.谢谢。	合作!			

電話: 27838351

http://www.konuaer.com

1. Scope

This specification shall cover the characteristics of 1-port SAW resonator with R433.92 used for remote-control security.

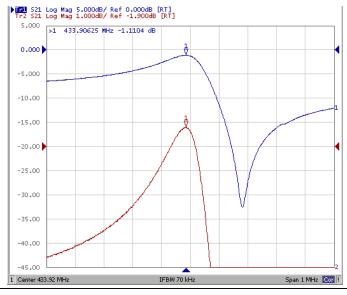
2. Electrical Specification

2.1 Maximum Rating

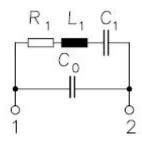
DC Voltage VDC	10V
AC Voltage Vpp	10V 50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
Source Power	0dBm

2.2 Electronic Characteristics

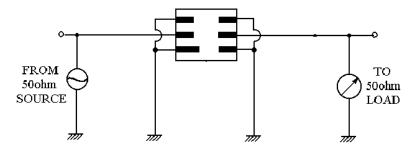
Item		Unites	Minimum	Typical	Maximum	
Center Frequency			MHz	433.845	433.92	433.995
Insertion Loss	S		dB		1.4	1.9
Ovality Factor Unload C		Unload Q		8000	12800	
Quality Facto	1	50Ω Loaded Q		1000	433.92 433.99 1.4 1.9	
Temperature	Turnov	Turnover Temperature		10	25	40
Stability	Freq.temp.Coefficient		ppm/℃		0.032	
Frequency Ag	ging		ppm/yr		<±10	
DC. Insulation	sulation Resistance			1.0		
RF	Motion	al Resistance R1	Ω		17	26
Equivalent	Motion	al Inductance L1	μΗ		70.743	
RLC Model	Motion	al Capacitance C1	fF		1.9018	
Transducer St	Transducer Static Capacitance C0				2.0	



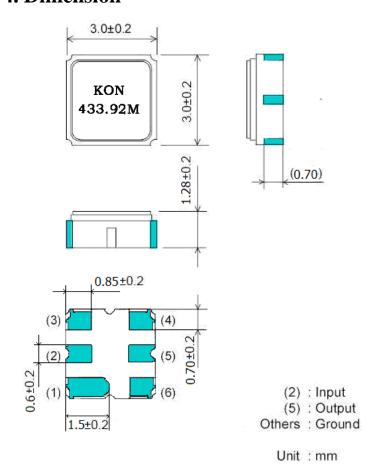
2.3 Equivalent LC Model



3. Test Circuit



4. Dimension



1. KON: Manufacture's logo

2. 433.92: Model code

5. Environment Characteristic

5-1 Thermal Shock:

The components shall remain within the electrical specifications after being kept at the condition of heat cycle conditions: TA=-40 °C ±3 °C, TB=85 °C ±2 °C, t1=t2=30min, switch time \leq 3min& cycle time : 100 times, recovery time: 2h±0.5h.

5-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 2.2.

5-3 Solder ability

Submerge the device terminals into the solder bath at 245° C $\pm 5^{\circ}$ C for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 2.2

5-4 The Temperature Storage:

- 5.3.1 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the $85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ for $96\text{h} \pm 4\text{h}$, recovery time : $2\text{h} \pm 0.5\text{h}$.
- 5.3.2 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the $-40^{\circ}\text{C} \pm 3^{\circ}\text{C}$ for 96h±4h, recovery time : 2h±0.5h.

5-5 Humidity test:

The components shall remain within the electrical specifications after being kept at the condition of ambient temperature $60^{\circ}\text{C} \pm 2^{\circ}\text{C}$, and $90 \sim 96\%$ RH for $96\text{h} \pm 4\text{h}$.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m for 3 times. The resonator shall fulfill the specifications in 2.2.

5-7 Vibration

Subject the device to the vibration for 2 hour each in X, Y and Z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The resonator shall fulfill the specifications in 2.2.

6. Remark

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

7. Packing

7.1 Dimensions

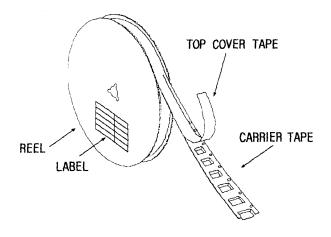
- (1) Carrier Tape: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

7.2 Reeling Quantity

1000 pcs/reel 7" 3000 pcs/reel 13"

7.3 Taping Structure

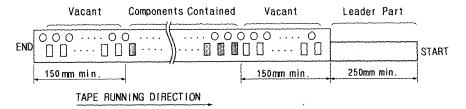
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

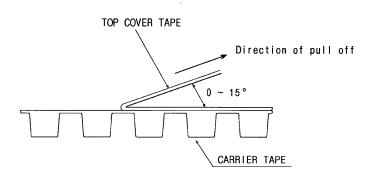
Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.

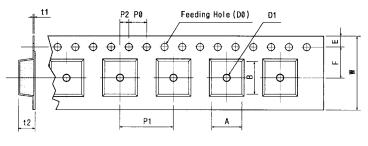


8. Tape Specifications

- 8.1 Tensile Strength of Carrier Tape: 4.4N/mm width
- 8.2 Top Cover Tape Adhesion (See the below figure)
 - (1) pull off angle: 0~15°(2) speed: 300mm/min.(3) force: 20~70g



[Figure 1] Carrier Tape Dimensions



Tape Running Direction

[Unit: mm]

W	F	Е	P0	P1	P2	D0	D1	t1	t2	A	В
12.0	5.5	1.75	4.0	4.0	2.0	Ø1.5	Ø1.0	0.3	1.25	3.3±	3.3±
±0.3	± 0.05	±0.1	±0.1	±0.1	± 0.05	±0.1	±0.25	± 0.05	±0.1	0.1	0.1

[Figure 2] Reel Dimensions

